



30V N-Channel Trench Power MOSFET

General Description

The SJP4468 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a wide variety of applications.

Features

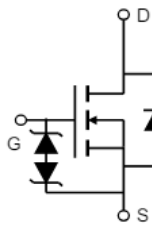
- Low Gate Charge
- High Power and current handling capability
- ESD Rating: HBM 2KV

Application

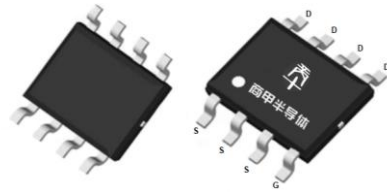
- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply

Key Performance Parameters

Parameter	Value	Unit
V_{DS}	30	V
$R_{DS(ON_TYP)}$	16.3	mΩ
I_D	10	A
Q_G	8.16	nC



Schematic Diagram



SOP-8 top&bottom view



Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJP4468	SJP4468	SOP-8	Tape	\	\	4000 Pcs

Table 1. Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	30	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	± 12	V
I_D	Drain Current-Continuous($T_C=25^\circ\text{C}$)	10	A
	Drain Current-Continuous($T_C=100^\circ\text{C}$)	6.2	A
$I_{DM}(\text{pluse})$	Drain Current-Continuous@ Current-Pulsed (Note 1)	40	A
P_D	Maximum Power Dissipation($T_C=25^\circ\text{C}$)	3.1	W
	Maximum Power Dissipation($T_C=100^\circ\text{C}$)	1.25	W
E_{AS}	Avalanche energy (Note 2)	25	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	$^\circ\text{C}$

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to- Case		40	$^\circ\text{C/W}$



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Table 3. Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V T _J =25℃			1	μA
		V _{DS} =30V, V _{GS} =0V T _J =125℃			100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±12V, V _{DS} =0V			±10	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.5		1.3	V
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =8A		15		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =6A T _J =25℃		17.4	23.1	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =2.5V, I _D =6A T _J =25℃		20.8	27.7	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =15V,V _{GS} =0V, f=1.0MHz		222		pF
C _{oss}	Output Capacitance			55.7		pF
C _{rss}	Reverse Transfer Capacitance			32		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=200KHz		1750		Ω
Switching Parameters						
t _{d(on)}	Turn-on Delay Time	V _{GS} =4.5V, V _{DS} =15V, R _L =1.25Ω, R _{GEN} =3Ω		11		nS
t _r	Turn-on Rise Time			34		nS
t _{d(off)}	Turn-Off Delay Time			55		nS
t _f	Turn-Off Fall Time			51		nS
Q _g	Total Gate Charge	V _{GS} =4.5V, V _{DS} =15V, I _D =8A		8.16		nC
Q _{gs}	Gate-Source Charge			2.5		nC
Q _{gd}	Gate-Drain Charge			4.4		nC
Source-Drain Diode Characteristics						
I _{SD}	Source-Drain Current (Body Diode)				10	A
V _{SD}	Forward on Voltage ^(Note 3)	V _{GS} =0V, I _S =8A			1	V

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

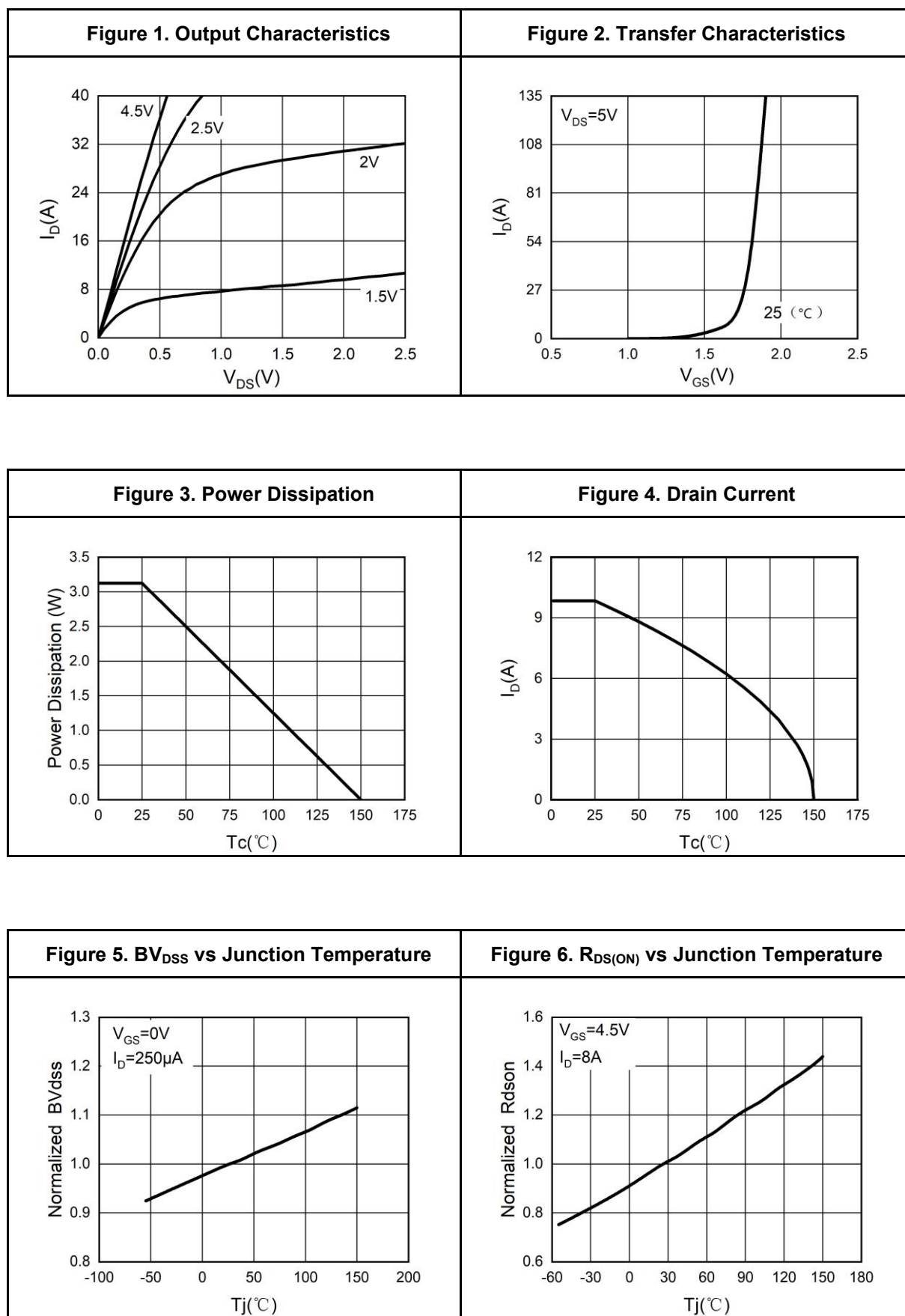
Notes 2.EAS condition: $T_J=25^{\circ}\text{C}, V_{DD}=10V, V_G=10V, R_g=25\Omega, L=0.5mH$.

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



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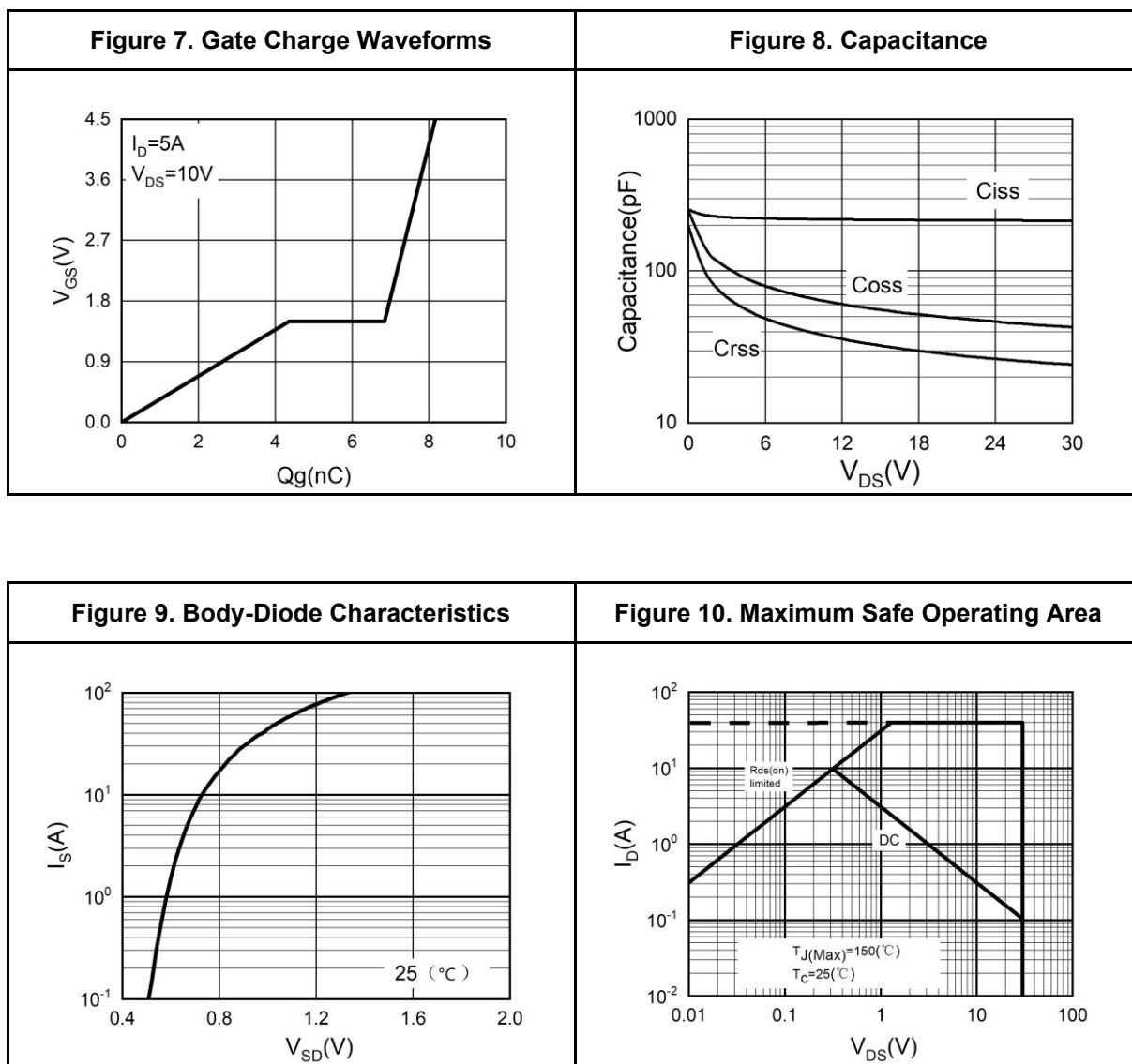
Typical Electrical And Thermal Characteristics (Curves)





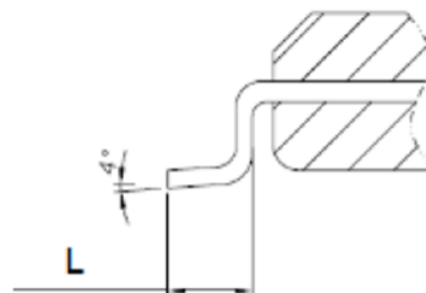
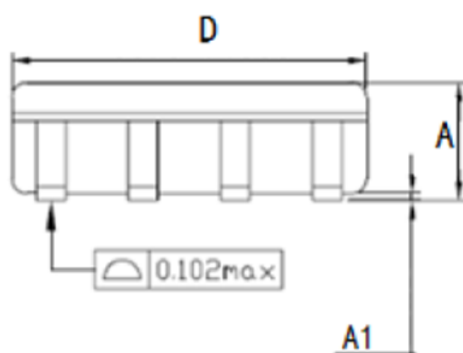
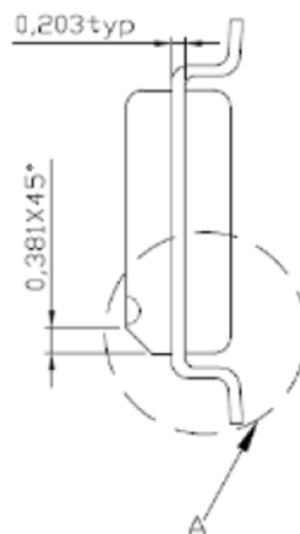
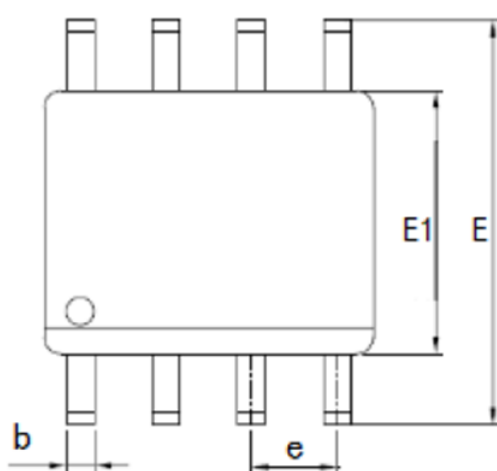
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Typical Electrical And Thermal Characteristics (Curves)





SOP-8 Package Information



A 局部放大

Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max
A	1.35	1.55	1.75
A1	0.1	0.15	0.2
b	0.346	0.406	0.466
D	4.8	4.89	4.98
E	5.75	6.00	6.25
E1	3.81	3.90	3.99
e	1.27TYP		
L	0.406	0.838	1.27



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